## WHAT IS CLAIMED IS:

1. A polishing composition for a substrate for memory hard disk, comprising silica particles in an aqueous medium, wherein the silica particles satisfy a relationship between an average particle size (r) of the silica particles on the number basis and a standard deviation ( $\sigma$ ) on the number basis of the following formula (1):

$$\sigma \ge 0.3 \times r \tag{1}$$

wherein r is an average particle size (nm) of the silica particles on the number basis, and σ is a standard deviation (nm) on the number basis, wherein the average particle size is obtained by a determination by transmission electron microscope (TEM) observation, and wherein a relationship between a particle size (R) and a cumulative volume frequency (V) in a range of particle sizes of from 60 to 120 nm satisfies the following formulas (2) and (3):

$$V \ge 0.5 \times R \tag{2}$$

$$V \le 0.25 \times R + 75 \tag{3}$$

wherein R is a particle size (nm) of the silica particles, and V is a cumulative volume frequency (%) counted from a small particle size side of the silica particles.

2. The polishing composition according to claim 1, wherein the silica particles are colloidal silica particles.

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- 3. The polishing composition according to claim 1, further comprising at least one member selected from the group consisting of acids, salts thereof and oxidizing agents.
- 5 4. The polishing composition according to claim 2, further comprising at least one member selected from the group consisting of acids, salts thereof and oxidizing agents.
- 5. The polishing composition according to claim 1, wherein a pH thereof is from 1 to 4.5.
  - 6. The polishing composition according to claim 2, wherein a pH thereof is from 1 to 4.5.
- 7. The polishing composition according to claim 3, wherein a pH thereof is from 1 to 4.5.
  - 8. The polishing composition according to claim 4, wherein a pH thereof is from 1 to 4.5.

9. A method of reducing microwaviness of a substrate for memory hard disk, comprising the step of polishing the substrate for memory hard disk with the polishing composition of claim 1.

10. A method of reducing microwaviness of a substrate for memory hard disk,

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comprising the step of polishing the substrate for memory hard disk with the polishing composition of claim 2.

11. A method of reducing microwaviness of a substrate for memory hard disk, comprising the step of polishing the substrate for memory hard disk with the polishing composition of claim 3.

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- 12. A method of reducing microwaviness of a substrate for memory hard disk, comprising the step of polishing the substrate for memory hard disk with the polishing composition of claim 4.
- 13. A method of reducing microwaviness of a substrate for memory hard disk, comprising the step of polishing the substrate for memory hard disk with the polishing composition of claim 5.
- 14. A method of reducing microwaviness of a substrate for memory hard disk, comprising the step of polishing the substrate for memory hard disk with the polishing composition of claim 6.
- 20 15. A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 1.
- 16. A method for manufacturing a substrate for memory hard disk,
  comprising the step of polishing an Ni-P plated substrate for memory hard disk

with the polishing composition of claim 2.

- 17. A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 3.
- 18. A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 4.

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- 19. A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 5.
- 20. A method for manufacturing a substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 6.